OKI Semiconductor

MSM54V16258B/BSL

262,144-Word x 16-Bit DYNAMIC RAM: FAST PAGE MODE TYPE WITH EDO

DESCRIPTION

The MSM54V16258B/BSL is a 262,144-word x 16-bit dynamic RAM fabricated in OKI's CMOS silicon gate technology. The MSM54V16258B/BSL achieves high integration, high-speed operation, and low-power consumption due to quadruple polysilicon double metal CMOS. The MSM54V16258B/BSL is available in a 40-pin plastic SOJ or 44/40-pin plastic TSOP.

FEATURES

- · Single3.3V power supply, ±0.3V tolerance
- · Input :TTL compatible
- · Output :TTL compatible, 3-state
- Refresh: 512 cycles/64ms
- · Fast page mode with EDO, read modify write capability
- Byte wide control: 2 CAS control
- · CAS before RAS refresh, Hidden refresh, RAS only refresh capability
- · CAS before RAS self-refresh capability (SL Version.)
- Pachage: 40-Pin 400 mil plastic SOJ (SOJ40-P-400) (Product: MSM54V16258B/BSL-xxJS)

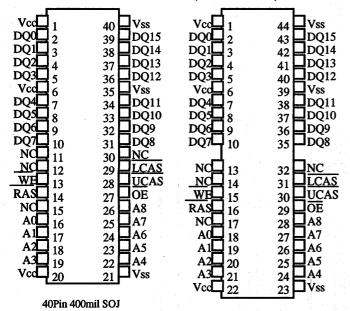
44/40-Pin 400 mil plastic TSOP (TSOP44/40-P-400/0.8-K) (Product : MSM54V16258B-xxTS-K)

(Product: MSM54V16258BSL-xxTSK) xx: indicates speed rank.

PRODUCT FAMILY

Family	A	ccess Tin	ne (Max.)		Cycle Tim	e (Min.)		
	trac	taa	t CAC	t oea	trc	thpc	Power Dissipation	
MSM54V16258B/BSL-40	40ns	22ns	10ns	10ns	80ns	15ns	432mW	
MSM54V16258B/BSL-45	45ns	24ns	12ns	12ns	90ns	17ns	396mW	
MSM54V16258B/BSL-50	50ns	26ns	12ns	14ns	100ns	20ns	360mW	

PIN CONFIGURATION (TOP VIEW)



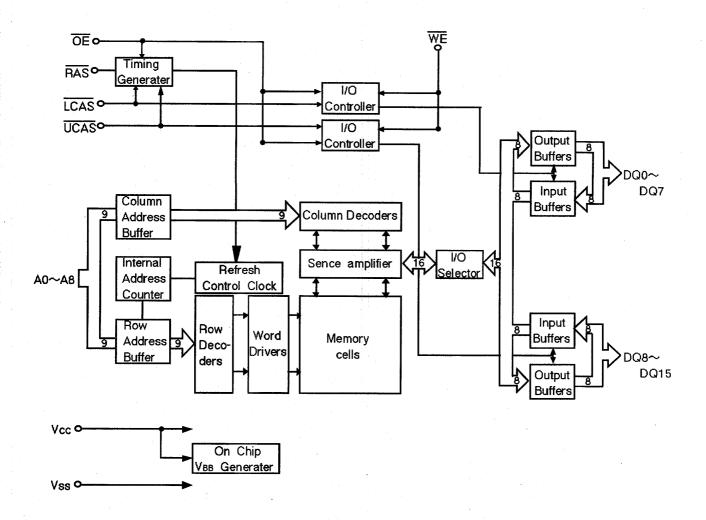
44/40Pin	400mil	TSOP

Pin Names	Function
A0-A8	Address Input
RAS	Row Address Strobe
LCAS,UCAS	Column Address Strobe
DQ0-15	Data-Input/ Data-Output
WE	Write Enable
<u>OE</u>	Output Enable
Vcc	Power Supply (3.3V)
Vss	Ground (0V)
NC	No Connection

Note1:

The same power supply voltage must be provided to every Vcc pin, and the same GND voltage level must be provided to every Vss pin.

BLOCK DIAGRAM



FUNCTION TABLE

						<u> </u>	-		
	Input Pin				DO)Pin	Functional Made		
RAS	LCAS	UCAS	WE	ŌĒ	DQ0~DQ7	DQ8~DQ15	Functinal Mode		
Н	*	*	*	*	High-Z	High-Z	Standby		
L	H	Н	*	*	High-Z	High-Z	Refresh		
L	L	Н	Н	L	Dout	High-Z	Lower Byte Read		
L	Н	L	Н	L	High-Z	Douт	Upper Byte Read		
L	L	L	Н	٦	Dout	Dout	Word Read		
L	L	Н	L	Н	DIN	Don't Care	Lower Byte Write		
L	Н	L	L	Н	Don't Care	Din	Upper Byte Write		
L	L	L	L	Н	Din	Din	Word Write		
L	L	L	Н	Н	High-Z	High-Z			

ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings

Rating	Symbol	Conditions	Value	Unit
Voltage on any pin relative to Vss	Vt.	Ta=25°C	-0.5~+4.6	٧
Short circuit output current	los	Ta=25°C	50	mΑ
Power dissipation	Po	Ta=25°C	1	W
Operrating temperrature	Topr	_	0~+70	ů
Storage temperature	Tstg	-	-55~+150	°C

Recommended Operating Conditions

(Ta=0°C to 70°C)

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage	Vcc	_	3.0	3.3	3.6	V
	Vss	_	0	0	0	V
Input high voltage	Vih		2.4	_	Vcc+0.3	٧
Input low voltage	Vil	_	-0.3	_	0.8	٧

Capacitance

(Vcc=3.3V±0.3V,Ta=25°C,f=1MHz)

Parameter	Symbol	Conditions	Тур.	Max.	Unit
Input capacitance (A0~A8)	Cint	. –	_	8	pf
Input capacitance (RAS, LCAS, UCAS, WE, OE)	Cin2	_	_	8	pf
Input / output capacitance (DQ0~DQ15)	C1/0	_	_	9	pf

DC CHARACTERISTICS

(Vcc=3.3V±0.3V , Ta=0 to 70℃)

D			MSM54V16258 B/BSL-40 Min. Max.		MSM54			V16258 SL-50		
Parameter	Symbol	Condition			Min.	Max.	Min.	Max.	Unit	Note
Output High Voltage	Vон	lон= - 1.0mA	2.4	Vcc	2.4	Vcc	2.4	Vcc	٧	
Output Low Voltage	Vol	loL= 2.0mA	0	0.4	0	0.4	0	0.4	٧	
Input Leakage Current	lu	0V≦Vin≦Vcc	-10	10	-10	10	-10	10	μΑ	
Output Leakage Current	Iro	DQi Disable 0V≦V₀≦5.5V	-10	10	-10	10	-10	10	μΑ	
Average Power Supply Current (Operating)	lcc ₁	RAS,CAS Cycling tnc=Min.		120		110	_	100	mA	1,2
Power Supply Current (Standby)	lcc2	RAS,CAS = VIH		2	_	2	_	2	mA	1
Average Power Supply Current (RAS only Refresh)	lccs	RAS=Cycling CAS=ViH trc=Min.	_	110	- -	100	_	90	mA	1,2
Average Power Supply Current (Fast Page Mode)	lcc4	RAS=VIL CAS Cycling thec=Min.	_	70	_	65	_	60	mA	1,3
Average Power Supply Current (CAS Before RAS Refresh)	lcc5	RAS=Cycling CAS Befor RAS		100	_	90		80	m A	1,2
Average Power Supply Current (Battery Backup)	Icce	tRC=125 μs CAS Befor RAS tRAS≦1 μs	- .	300	-	300	_	300	μΑ	1,2,4,5
Average Power Supply Current (CAS Before RAS Self-Refresh)	lccs	RAS=VIL CAS=VIL	- -	300	-	300	- <u>-</u>	300	μΑ	1,2,4,5

Notes: 1. Icc Max. is specified as Icc for the output open cindition

^{2.} Address can be changed once or less while RAS=VIL.

^{3.} Address can be changed once or less while CAS=VIH.

^{4.} Vcc-0.2V \leq VIH \leq 6.5V, -1.0V \leq VIL \leq 0.2V.

^{5.} SL version.

AC CHARACTERISTICS (1/2)

 $(Vcc = 3.3V \pm 0.3V, Ta = 0\sim70^{\circ}C)$

		MSM54V16258 MSM54V16258				$(\text{Vcc} = 3.3\text{V} \pm 0.3\text{V},$ MSM54V16258			0~70 C)
Parameter	Symbol	B/BS		B/BS		B/BS		Unit	Note
		MIN	MAX	MIN	MAX	MIN	MAX		11010
Random read or write cycle time	tric	80		90	_	100	_	ns	
Read/Write cycle time	trmw	115	_	130	_	145	_	ns	
Fast page mode cycle time	tнрс	15	_	17	_	20	_	ns	
Fast page mode read/write cycle time	tprmw	55		60		65	_	ns	
Access time from RAS	trac	_	40	-	45	_	50	ns	7,12,13
Access time from CAS	tcac	_	10	-	12		14	ns	7,12
Access time from column address	taa		22	_	24		26	ns	7,13
Access time from OE	t OEA	_	10	_	12		14	ns	
Access time from CAS precharge	tcpa .	-	24	. —	26		28	ns	7,12
Output low impedance time from CAS	tcLz	0	_	0	-	0	_	ทธ	
Data hold after CAS low	tсон	3	_	3	_	3	_	ns	17
Output buffer turn-off delay time	toff	3	8	3	8	3	8	ns	8
Output buffer turn-off delay time from OE	toez	3	8	3	8	3	8	ns	8
Output buffer turn-off delay time from RAS	trez	3	8	3	8	3	8	ns	8
Output buffer turn-off delay time from WE	twez	3	8	3	8	3	8	ns	8
Transition time	tr	2	35	2	35	2	35	ns	
Refresh preiod	tref	_	64		64	_	64	ms	
RAS precharge time	tap	30	_	35	_	40	_	ns	
RAS pulse width	TRAS	40	10,000	45	10,000	50	10,000	ns	
RAS pulse width (Fast page mode)	trasp	. 40	100,000	45	100,000	50	100,000	ns	
RAS hold time	tasa	8	_	10		10	_	ns	
RAS hold time reference to OE	tвон	8	_	- 8	_	10	_	ns	
CAS precharge time	t CP	5	_	6	_	7	_	ns	
CAS pulse width	tcas	6	10,000	7	10,000	8	10,000	ns	
CAS hold time	tсsн	40	_	45		50	_	ns	
CAS to RAS precharge time	tcrp	5	_	5	•••	5	. –	ns	
RAS to CAS delay time	trco	18	30	18	33	20	38	ns	12
RAS to column address delay time	trad	13	18	13	21	15	24	ns	
Row address set-up time	tasa	0	_	0	_	0		ns	13
Row address hold time	trah	8		8	_	10		ns	
Column address set-up time	tasc	0	_	0	-	0		ns	
Column address hold time	tcah	5	_	6	_	8	_	ns	
Column address hold time from RAS	t ar	30	_	30	-	35		ns	
Column address to RAS lead time	TRAL	22	_	24		26	_	ns	
Read command set-up time	trics	0		0	_	0	_	ns	
Read command hold time	tach	0	- 1	0	-	0		ns	9
Read command hold time reference to RAS	trrh	0	-	0	<u>-</u>	0	_	ns	9
WE pulse width	twep	10		10		10	_	ns	

AC CHARACTERISTICS (2/2)

 $(Vcc = 3.3V \pm 0.3V, Ta = 0 \sim 70^{\circ}C)$

Parameter	Symbol	MSM54V16 Symbol B/BSL-40		MSM54 B/BS	V16258 L-45		4V16258 SL-50	Unit	Note
	Joynnbor	MIN	MAX	MIN	MAX	MIN	MAX	1	11010
Write command set-up time	twcs	0		0	_	0	_	ns	
Write command hold time	twch	7	_	8	_	9	_	ns	
Write command pulse width	twp	7	_	8	_	9	-	ns	
Write command hold time from RAS	twcn	30	_	30	_	35		ns	
OE command hold time	toeh	7		- 8		9		ns	
Write command to CAS lead time	tcwL	7	_	8		9	_	ns	
Write command to RAS lead time	trwL	8	-	12	_	14	_	ns	
Data to CAS delay time	tozc	0	_	0	_	0	_	ns	
Data to BE/OE delay time	tozo	0	_	0	_	0	_	ns	
Data-in set-up time	tos	0		0		0		ns	10
Data-in hold time	tрн	6	_	7	-	8		ns	10
Data-in hold time referenced to RAS	tohr	30	_	30		35		ns	
OE to Data delay time	toed	8		8	_	8		กร	
OE "L" to CAS "H" lead time	tосн	10	_	10	-	10	_	ns	
CAS "H" to OE "L" lead time	tсно	10	_	10	_	10	_	ns	
Hi-Z command pulse width	toep	10	_	10	_	10	_	ns	
CAS to WE delay time	tcwn	28	_	30	_	32	_	ns	11
Column address to WE delay time	tawd	38	_	40	_	44	_	ns	11
RAS to WE delay time	trwd	5 5		60	_	65	-	ns	11
CAS active delay time from RAS precharge	tnpc	0	. –	0	_	0	_	ns	
RAS to CAS set-up time (CAS before RAS)	tcsR	10	_	10	_	10	_	ns	
RAS to CAS hold time (CAS before RAS)	tсня	10	-:.	. 10		10		ns	
RAS pulse width (CAS before RAS self-refresh)	trass	100	_	100		100		us	19
RAS precharge time (CAS before RAS self-refresh)	taps	100	-	100		100	_	ns	19
CAS hold time (CAS before RAS self-refresh)	tcus	-40	_	-40	_	-40		ns	19

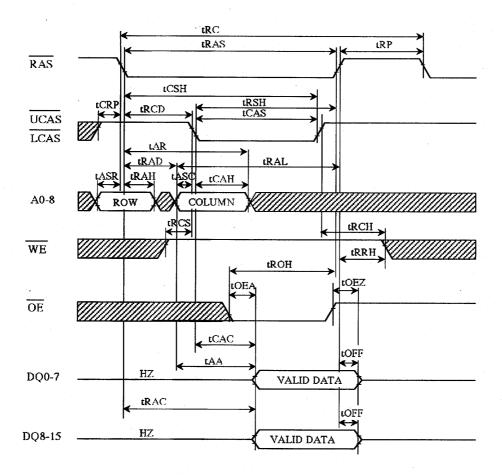
Notes:

- 1. All voltages are referenced to Vss.
- 2. This parameter is dependent upon the cycle rate.
- 3. This parameter is dependent upon the output loading. Specified values are obtained with the output open.
- 4. An initial pause of 200 μs is required after power-up, followed by any 8RAS cycles. (Example: RAS-only-refresh) before proper device operation is achieved. In case of using internal refresh counter, a minimum of 8CAS before RAS cycles instead of 8RAS cycles are required.
- 5. The AC characteristics assume tr=5ns.
- 6. Vih (Min.) and Vil. (Max.) are reference levels for measuring timing of input signals. Also, transition times are measured between V iii and Vii.
- Data outputs are measured with a load of 30 pF.
 DOUT reference levels: VoH/VoL=1.8V/1.4V.
- 8. trez (Max.), toff (Max.), twez (Max.) and toez (Max.) define the time at which the outputs achieve the open circuit condition and are not referebced to output voltage levels.

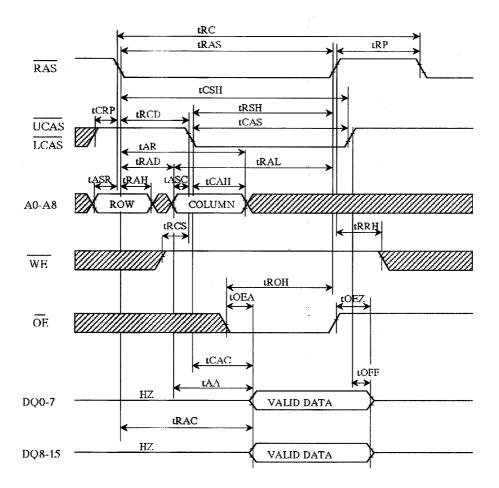
 This parameter is sampled and not 100 % tested.
- 9. Either tren or trrn must be satisfied for a read cycle.
- 10. These parameters are referenced to CAS leading edge of early write cycles and to WE leading edge in OE-controlled write cycles and read-modify-write cycles.
- 11. twos, txwb, tcwb and tawb are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If twos≥twos (Min.), the cycle is an early write cycle and the data out pins will remain open circuit throughout the entire cycle.

 If txwb≥txwb (Min.), tcwb≥tcwb (Min.) and tawb≥tawb (Min.), the cycle is a read-modify-write cycle and the data out will contain data read from the selected cell. If neither or the above sets of conditions is satisfied, the condition of the data out is indetermunate.
- 12. Operation within the trop (Max.) limit insures that trac (Max.) can be met. trop (Max.) is specified as a reference point only. If trop is greater than the specified trop (Max.) limit, then access time is controlled by topo.
- 13. Operation within the trad (Max.) limit ensures that trac (Max.) can be met. trad (Max.) is specified as a reference point only: If trad is greater than the specified trad (Max.) limit, then access time is controlled by trad.
- 14. Input levels at the AC testing are 3.0V/0V.
- 15. Addresses (A0 A8) may be changed two times or less while RAS = V II.
- 16. Addresses (A0 A8) may be changed once or less while $\overline{CAS} = V$ III and $\overline{RAS} = VIII.$
- 17. This is guaranteed by design. (toon=toac output transition time). This parameter is not 100 % tested.
- 18. This parameter is dependent upon the number of address transitions. Specified values are measured with a maximum of two transitions per address cycle in Fast Page Mode.
- 19. SL version.

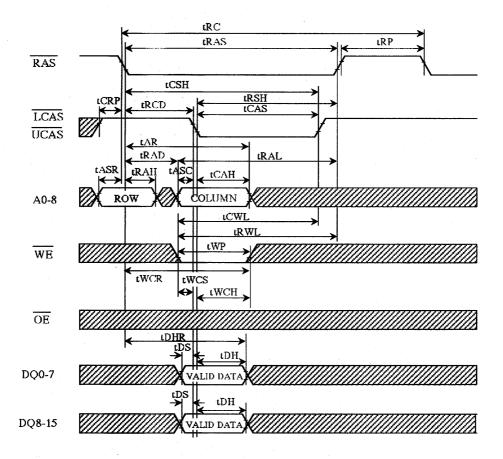
READ CYCLE (RAS output control)



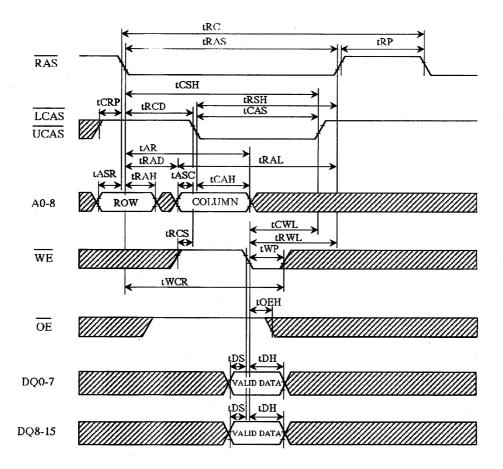
READ CYCLE (CAS output control)



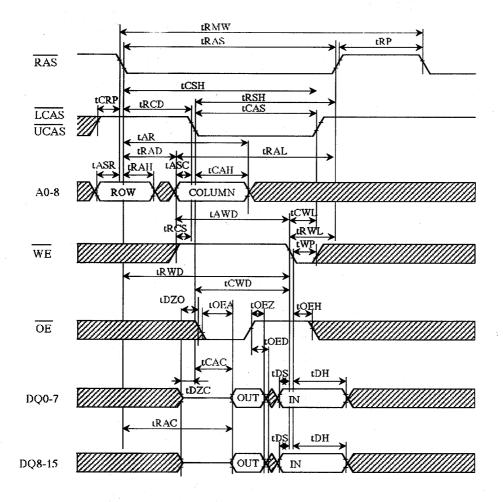
EARLY WRITE CYCLE (LCAS and UCAS active)



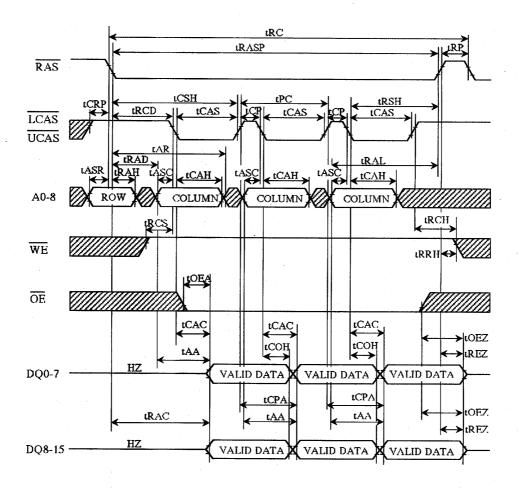
LATE WRITE CYCLE (LCAS and UCAS active)



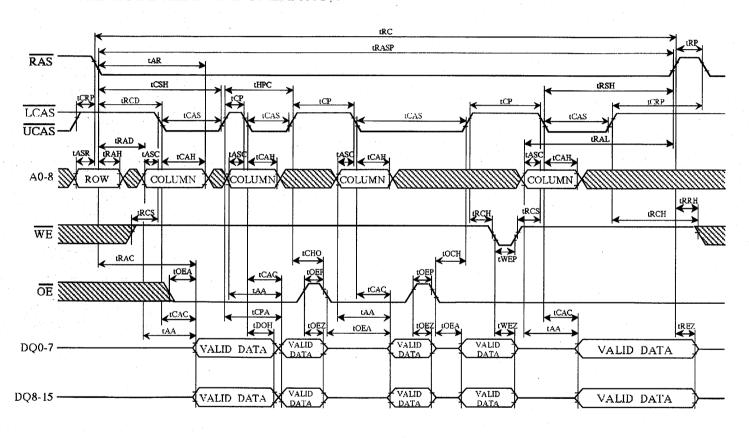
READ MODIFY WRITE CYCLE (LCAS and UCAS active)



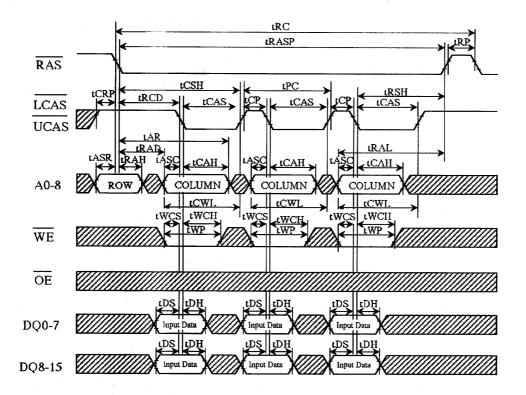
FAST PAGE MODE READ CYCLE with Extended Data Out



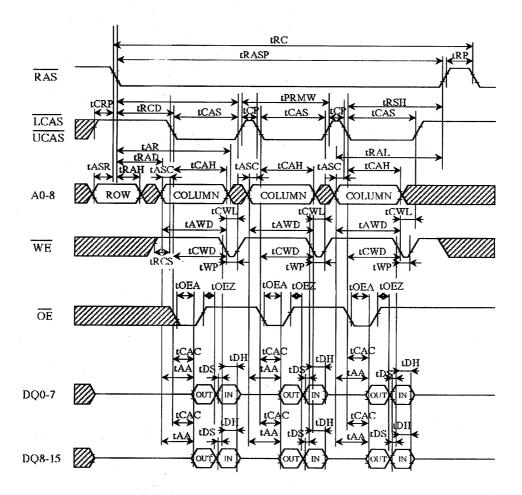
FAST PAGE MODE READ HI-Z OPERATION



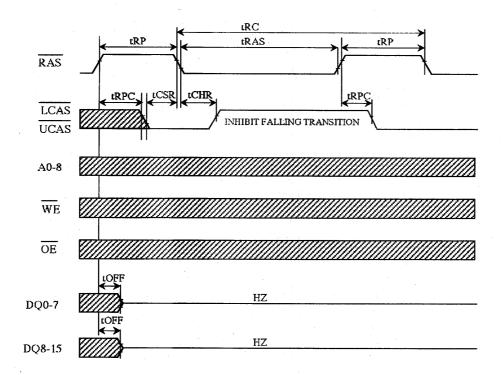
FAST PAGE MODE EARLY WRITE CYCLE



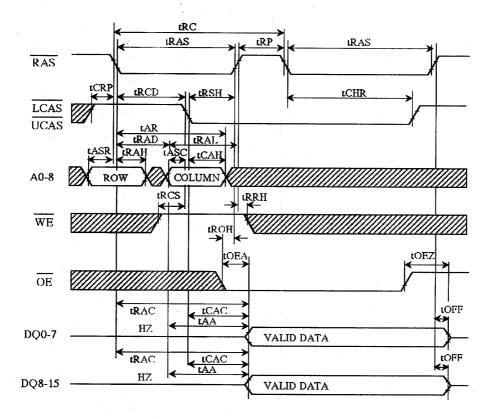
FAST PAGE MODE READ MODIFY WRITE CYCLE



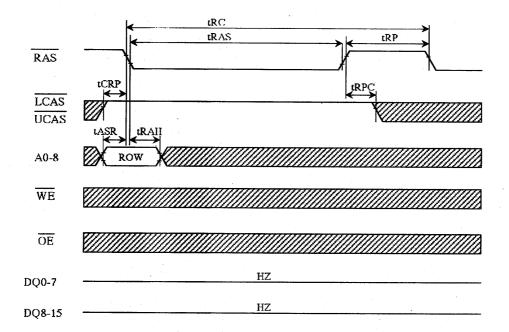
CAS BEFORE RAS REFRESH CYCLE



HIDDEN REFRESH CYCLE

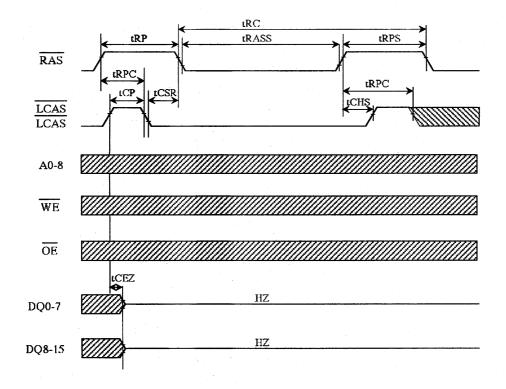


RAS ONLY REFRESH CYCLE



 $\qquad \qquad : \ ^{"}\!H" \ \text{or} \ ^{"}\!L" \\$

CAS BEFORE RAS SELFREFRESH CYCLE



: "H" or "L"

NOTE: SL version.